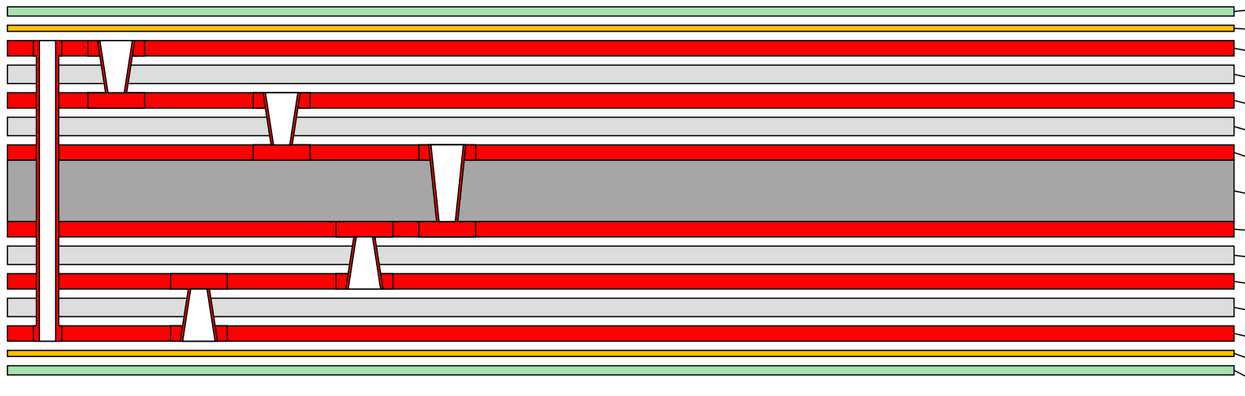

#	Layer	Thickness	Description	Note
	Top Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts
	Top Surface Finish	0.006mm		
1	Top Side	0.025mm	Starting foil 1/4oz. after plating and processing	
		0.030mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
2	Inner Layer 1	0.025mm	Starting foil 1/4oz. after plating and processing	
		0.030mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
3	Inner Layer 2	0.025mm	Starting foil 1/4oz. after plating and processing	
		0.100mm	Core IPC-4101/127/128	FR-4.1 filled, halogen free
4	Inner Layer 3	0.025mm	Starting foil 1/4oz. after plating and processing	
		0.030mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
5	Inner Layer 4	0.025mm	Starting foil 1/4oz. after plating and processing	
		0.030mm	Prepreg IPC-4101/127/128	FR-4.1 filled, halogen free
6	Bottom Side	0.025mm	Starting foil 1/4oz. after plating and processing	
	Bottom Surface Finish	0.006mm		
	Bottom Solder	0.015mm	Soldermask IPC-SM840	used on rigid parts

Total thickness: 0.411mm

notes:

Standard: Only microvias, NO PTHs
With PTH Copper 35 µm thick on Top/Bottom

Standard: Surface Finish ENIG
(Ni 5.5 µm ± 1.5 µm, Au 0.075 µm ± 0.025 µm)

Final copper thicknesses according to IPC-6012

Please follow our sectional design rules:
► www.we-online.com/designrulesslimhdi_en

HDI6_2-2b-2_041_25_2V13

PCB Thickness Tolerance: ± 10%

customer		**created**	
pcb name		**approved**	
engineer		**format**	**A4, landscape**
date			

Template Revision: 10/2023 by Andreas Schilpp / Michael Kress / Werner Öchslen

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MORE THAN YOU EXPECT